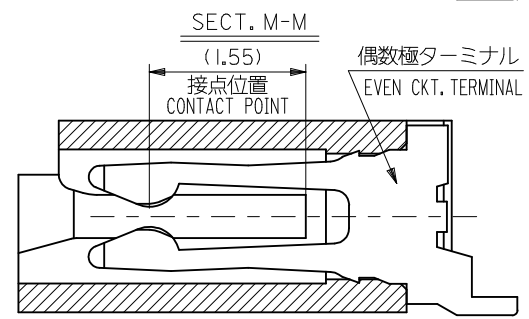
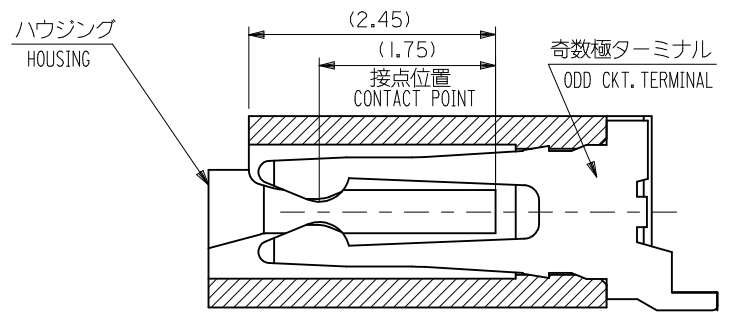
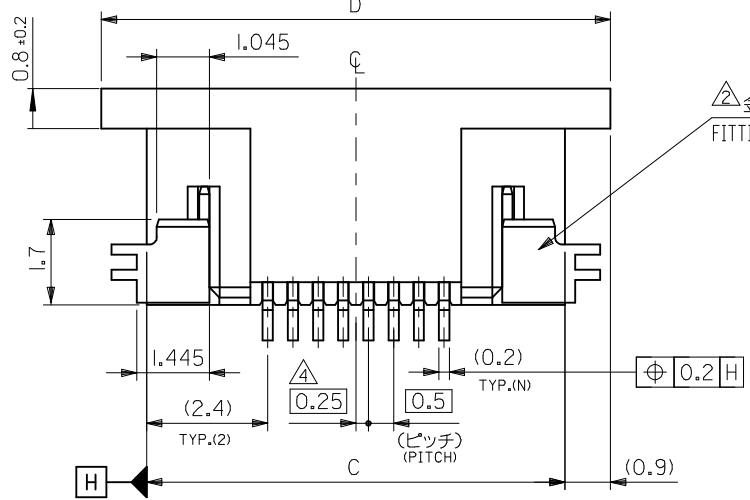
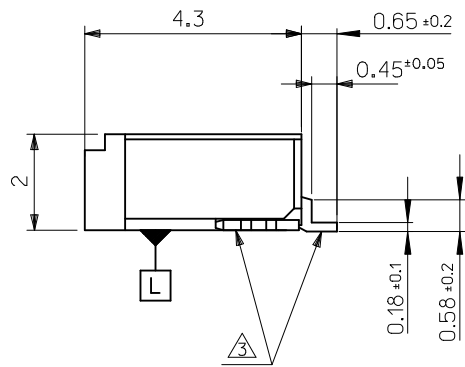
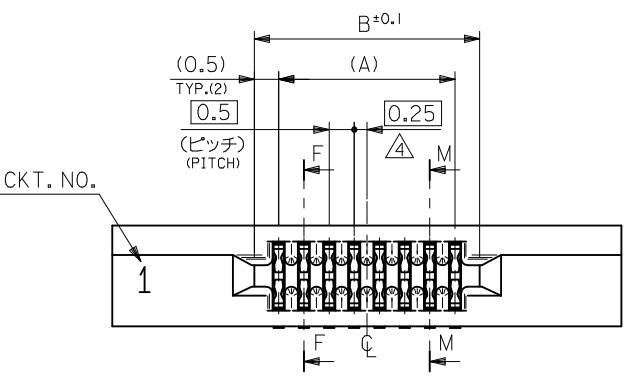
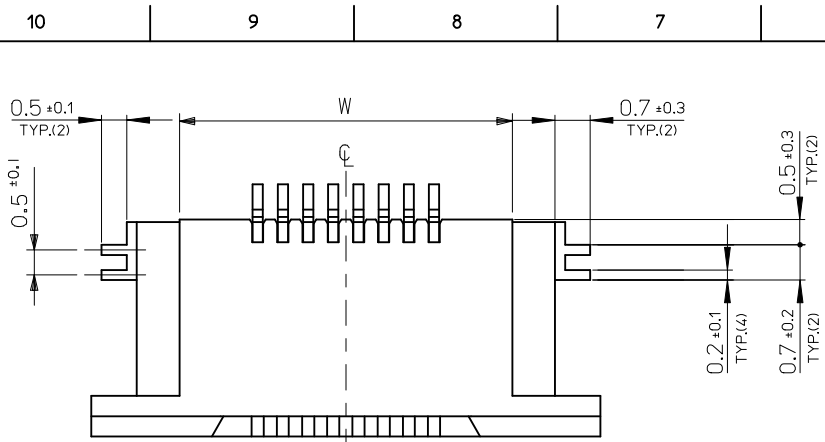


- 注記(NOTES)
1. 使用材料 (MATERIAL)
ターミナル (TERMINAL): リン青銅
PHOSPHOR BRONZE ± 0.2
錫ビスマスマスメッキ 1. 0マイクロメートル以上
TIN-BISMUTH 1.0 MICROMETER MINIMUM
ニッケル下地 1. 0マイクロメートル以上
NICKEL (UNDER PLATING) 1.0 MICROMETER MINIMUM
ハウジング (HOUSING): 46ナイロン (46NYLON), UL 94V-0
金具 (FITTING NAIL): リン青銅
PHOSPHOR BRONZE ± 0.2
錫メッキ 1. 0マイクロメートル以上
TIN 1.0 MICROMETER MINIMUM
ニッケル下地 1. 0マイクロメートル以上
NICKEL (UNDER PLATING) 1.0 MICROMETER MINIMUM
 2. パターン剥離止め用金具。(FITTING NAIL FOR PREVENTION OF PEELING OFF PCB, PATTERN.)
ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 L に対し上方向 0.1MAX、下方向 0.15MAX、とする。
 3. MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM L
UPPER DIRECTION 0.1MAX., LOWER DIRECTION 0.15MAX.
偶数極に適用。(TO BE APPLIED ONLY WHEN ALL CKTS. ARE EVEN.)
 5. 本製品は 52689-***40 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE 52689-***40.

MODEL NO. 52689-***49

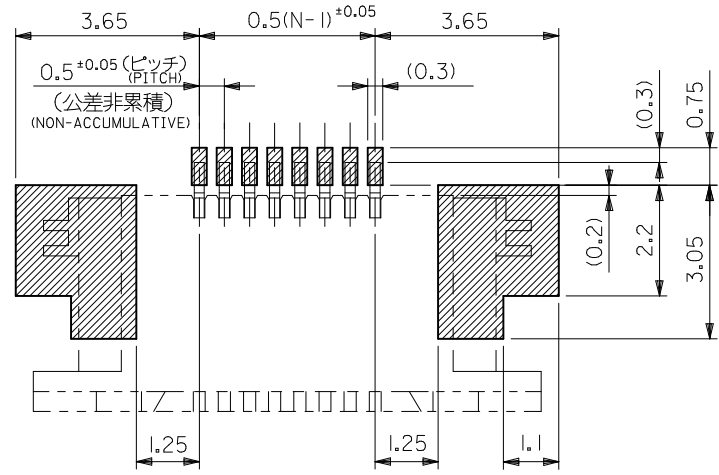
REVISED EC NO: J2017-0300 DRWNGES CHKD: APPR:MSASAO	2016/12/01 2016/12/20	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		0.25 UNDER	UNDER	±	DRAWN BY H. KAWABATA	DATE '04/02/03	TITLE 0.5 FPC CONN NON ZIF HSG ASSY FOR SMT(R/A) -LEAD FREE-		
		0.25 OVER	0.5 UNDER	±	CHECKED BY K. TOJO	DATE '04/02/03	DOCUMENT NO. SD-52689-034		
		0.5 OVER	1.0 UNDER	±	APPROVED BY M. SASAO	DATE '04/02/03			
		0 OVER	10 UNDER	±0.2	MATERIAL NO. SEE SHEET 2		SHEET NO. 1 OF 2		
		10 OVER	30 UNDER	±0.25	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				
		30 OVER		±0.3					
G		ANGULAR		±3 °	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



- 注記(NOTES)
1. 使用材料 (MATERIAL)
ターミナル (TERMINAL): リン青銅
PHOSPHOR BRONZE ± 0.2
錫ビスマスマスメッキ 1. 0マイクロメートル以上
TIN-BISMUTH 1.0 MICROMETER MINIMUM
ニッケル下地 1. 0マイクロメートル以上
NICKEL (UNDER PLATING) 1.0 MICROMETER MINIMUM
ハウジング (HOUSING): 46ナイロン (46NYLON), UL 94V-0
金具 (FITTING NAIL): リン青銅
PHOSPHOR BRONZE ± 0.2
錫メッキ 1. 0マイクロメートル以上
TIN 1.0 MICROMETER MINIMUM
ニッケル下地 1. 0マイクロメートル以上
NICKEL (UNDER PLATING) 1.0 MICROMETER MINIMUM
 2. パターン剥離止め用金具。(FITTING NAIL FOR PREVENTION OF PEELING OFF PCB, PATTERN.)
ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 L に対し上方向 0.1MAX、下方向 0.15MAX、とする。
 3. MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM L
UPPER DIRECTION 0.1MAX., LOWER DIRECTION 0.15MAX.
偶数極に適用。(TO BE APPLIED ONLY WHEN ALL CKTS. ARE EVEN.)
 5. 本製品は 52689-***40 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE 52689-***40.

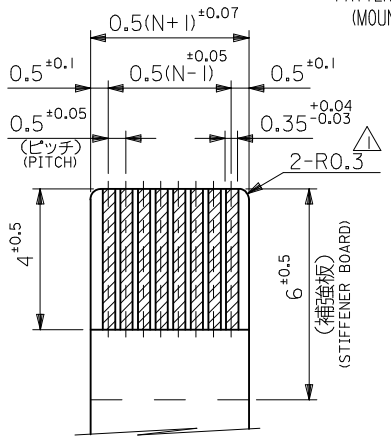
MODEL NO. 52689-***49

REVISED EC NO: J2017-0300 DRWNGS CHKD: APPR:MSASAO	2016/12/01 2016/12/20	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		0.25 UNDER UNDER \pm	0.25 OVER 0.5 UNDER \pm	0.5 OVER 1.0 UNDER \pm	0 OVER 10 UNDER ± 0.2	10 OVER 30 UNDER ± 0.25	30 OVER ± 0.3	ANGULAR $\pm 3^\circ$	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS
DESCRIPTION		DRAWN BY H. KAWABATA		DATE '04/02/03		TITLE 0.5 FPC CONN NON ZIF HSG ASSY FOR SMT(R/A) -LEAD FREE-			
		CHECKED BY K. TOJO		DATE '04/02/03					
		APPROVED BY M. SASAO		DATE '04/02/03					
		MATERIAL NO.		SEE SHEET 2		DOCUMENT NO. SD-52689-034		SHEET NO. 1 OF 2	

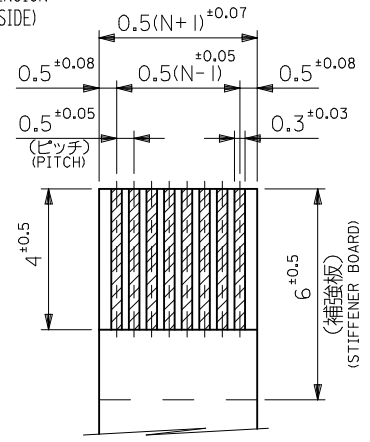


参考基板レイアウト
(マウント面)

REFERENCE P.C. BOARD
PATTERN DIMENSION
(MOUNTING SIDE)



適合FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)



適合FFC推奨寸法
APPLICABLE FFC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)

FPCについて:
打抜き方向は導体側から補強板側を推奨致します。
補強フィルム材質はポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。

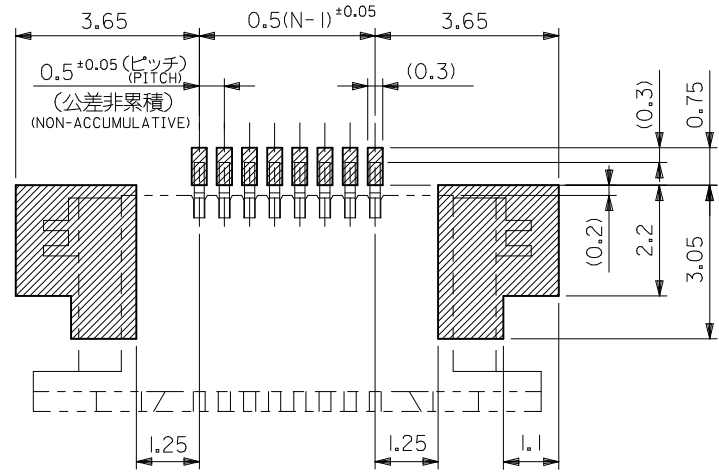
ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION : FORM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED MATERIAL :
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

注記 NOTES

△ R0.3は、FPCの導体部にかからないこと。
R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.

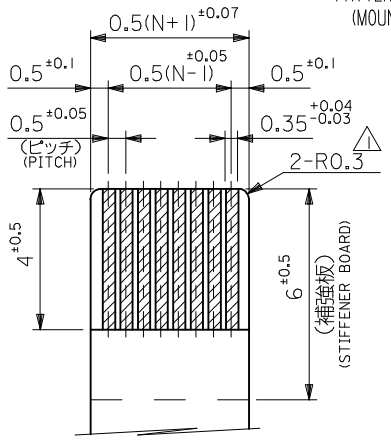
52689-***49	17.6	21.1	19.3	15.5	14.5	52689-3087	52689-3049	30
MODEL NO.	W	D	C	B	A	EMBOSSED TAPE	MATERIAL NO.	極数 CKT.
	13.6	17.1	15.3	11.5	10.5	ORDER No. オーダー番号	52689-2287	52689-2249

REVISED EC NO: J2017-0300 DRAWINGS CHKD: APPR: MSASAO	DESCRIPTION 2016/12/01 2016/12/20	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		0.25 UNDER UNDER ±	0.25 OVER 0.5 UNDER ±	DRAWN BY H. KAWABATA	DATE '04/02/03	TITLE 0.5 FPC CONN NON ZIF HSG ASSY FOR SMT(R/A) -LEAD FREE-			
		0.5 OVER 1.0 UNDER ±	0 OVER 10 UNDER ±0.2	CHECKED BY K. TOJO	DATE '04/02/03				
		10 OVER 30 UNDER ±0.25	30 OVER ±0.3	APPROVED BY M. SASAO	DATE '04/02/03				
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	SEE TABLE		DOCUMENT NO. SD-52689-034	SHEET NO. 2 OF 2	

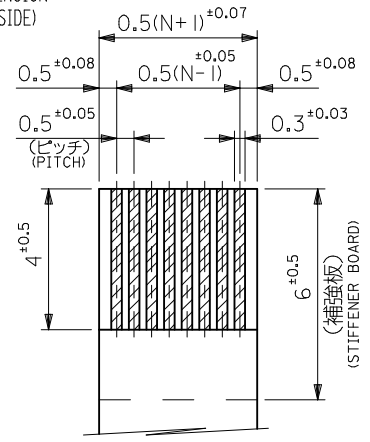


参考基板レイアウト
(マウント面)

REFERENCE P.C. BOARD
PATTERN DIMENSION
(MOUNTING SIDE)



適合FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)



適合FFC推奨寸法
APPLICABLE FFC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)

FPCについて:
打抜き方向は導体側から補強板側を推奨致します。
補強フィルム材質はポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION : FORM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED MATERIAL :
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

注記 NOTES

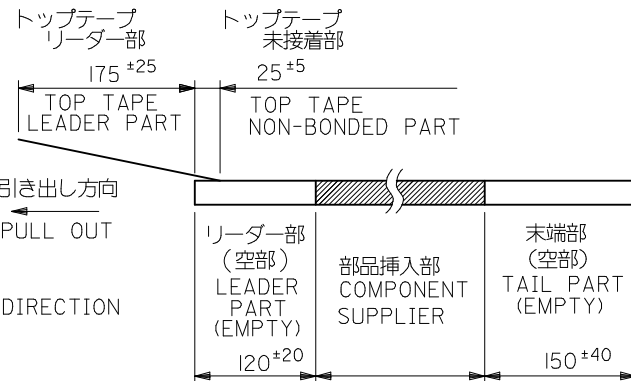
△ R0.3は、FPCの導体部にかからないこと。
R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.

52689-***49	17.6	21.1	19.3	15.5	14.5	52689-3087	52689-3049	30
MODEL NO.	13.6	17.1	15.3	11.5	10.5	52689-2287	52689-2249	22
	W	D	C	B	A	EMBOSSED TAPE	MATERIAL NO.	極数 CKT.
						ORDER No. オーダー番号		

REVISED EC NO: J2017-0300 DRAWINGS CHKD: APPR: MSASAO	2016/12/01	2016/12/20	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±	DRAWN BY	DATE	TITLE	0.5 FPC CONN NON ZIF HSG ASSY FOR SMT(R/A) -LEAD FREE- molex DOCUMENT NO. SD-52689-034 SHEET NO. 2 OF 2		
	0.25 OVER	0.5 UNDER	±	H. KAWABATA	'04/02/03				
	0.5 OVER	1.0 UNDER	±	CHECKED BY	DATE				
	0 OVER	10 UNDER	±0.2	K. TOJO	'04/02/03				
10 OVER	30 UNDER	±0.25	APPROVED BY	DATE					
30 OVER		±0.3	M. SASAO	'04/02/03					
	ANGULAR	±3 °	MATERIAL NO.		SEE TABLE				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

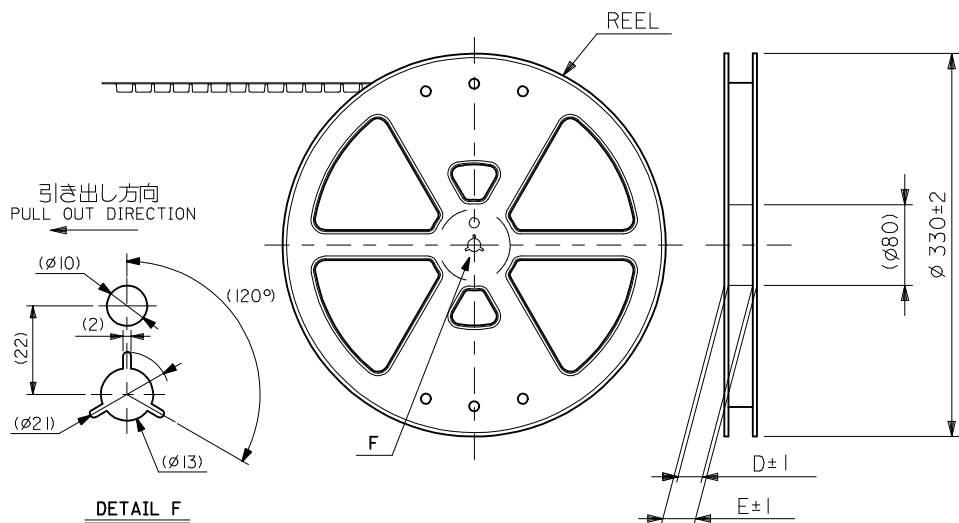
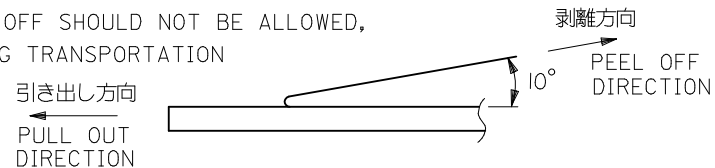
注記 NOTES

- 製品詳細寸法については図面 SD-52689-034 を参照下さい。
RE DETAILED DIMENSION,SEE SD-52689-034.
- 梱包数量：1000個/リール
NUMBER OF CONNECTORS:1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



- トップテープの剥離強度：(剥離方向は下図参照)
0.1~1.3N {10~130gf}
尚、本規格値は、出荷時に適用。(但し、輸送時に剥離が発生しない事。)

PEELING OFF FORCE OF TOP TAPE
0.1~1.3N {10~130gf} (PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT
PEEL OFF SHOULD NOT BE ALLOWED,
DURING TRANSPORTATION



DETAIL F

- 材料
キャリアテープ：ポリプロピレン (PP)
トップテープ：PET, PE, PEF
リール：ポリスチレン (PS) <リサイクル材を含む>

MATERIAL CARRIER TAPE:POLYPROPYLENE
TOP TAPE:PET,PE,PEF
REEL:POLYSTYREN(PS)
<RECYCLE MATERIAL CONTAINED>

- 本製品は52689-***93の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 52689-***93.

- FPCについて：
打抜き方向は導体側から補強板側を推奨致します。
補強フォルム材質はポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。

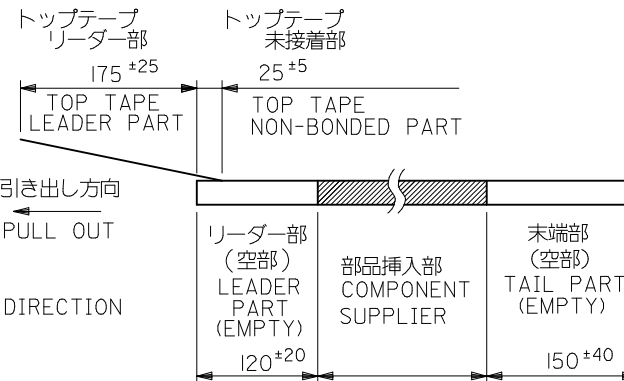
ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION :
FORM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED MATERIAL :
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

- 本製品は乾燥剤入り、ハイバリア梱包仕様である。
THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.

REVISED EC NO: J2017-0300 DRAWINGS CHKD: APPR:MSASAO	DESCRIPTION 2016/12/01 2016/12/20	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		0.25 UNDER UNDER ±0.03	0.25 OVER 0.5 UNDER ±0.05	0.5 OVER 1.0 UNDER ±0.1	1.0 OVER 10 UNDER ±0.2	10 OVER 30 UNDER ±0.25	30 OVER ±0.3	ANGULAR ±3	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE A3
				DRAWN BY H.KAWABATA	DATE 2004/02/03	TITLE 0.5 FPC CONN NON ZIF HSG ASSY SMT RA EMBSTP PKG -LEAD FREE-				
				CHECKED BY K.TOJO	DATE 2004/02/03					
				APPROVED BY M.SASAO	DATE 2004/02/03				DOCUMENT NO. SD-52689-035	

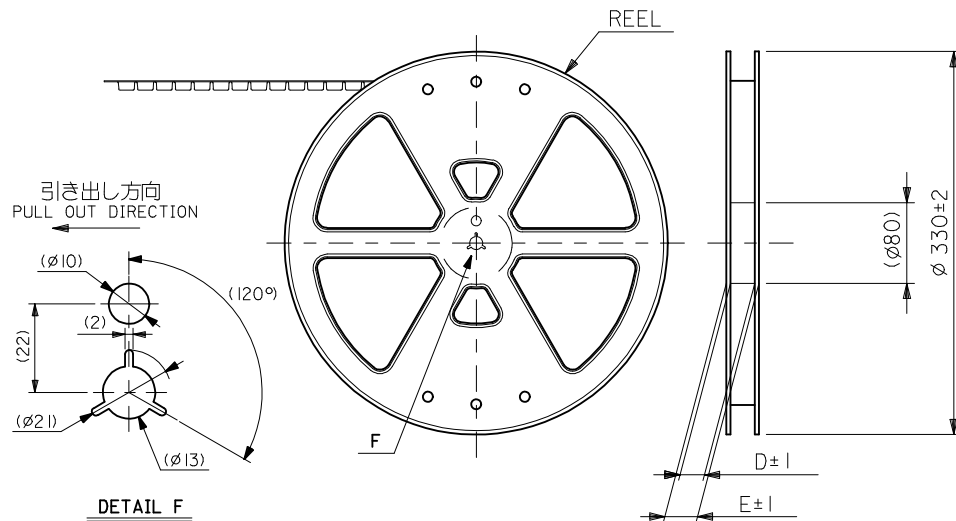
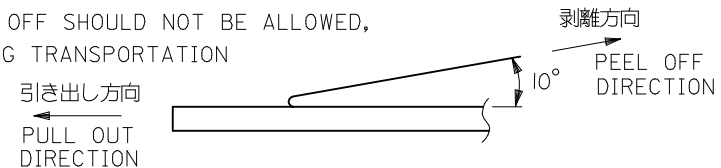
注記 NOTES

- 製品詳細寸法については図面 SD-52689-034 を参照下さい。
RE DETAILED DIMENSION,SEE SD-52689-034.
- 梱包数量：1000個/リール
NUMBER OF CONNECTORS:1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



- トップテープの剥離強度：(剥離方向は下図参照)
0.1~1.3N {10~130gf}
尚、本規格値は、出荷時に適用。(但し、輸送時に剥離が発生しない事。)

PEELING OFF FORCE OF TOP TAPE
0.1~1.3N {10~130gf} (PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT
PEEL OFF SHOULD NOT BE ALLOWED,
DURING TRANSPORTATION



- 材料
キャリアテープ：ポリプロピレン (PP)
トップテープ：PET, PE, PEF
リール：ポリスチレン (PS) <リサイクル材を含む>

MATERIAL CARRIER TAPE:POLYPROPYLENE
TOP TAPE:PET,PE,PEF
REEL:POLYSTYREN(PS)
<RECYCLE MATERIAL CONTAINED>

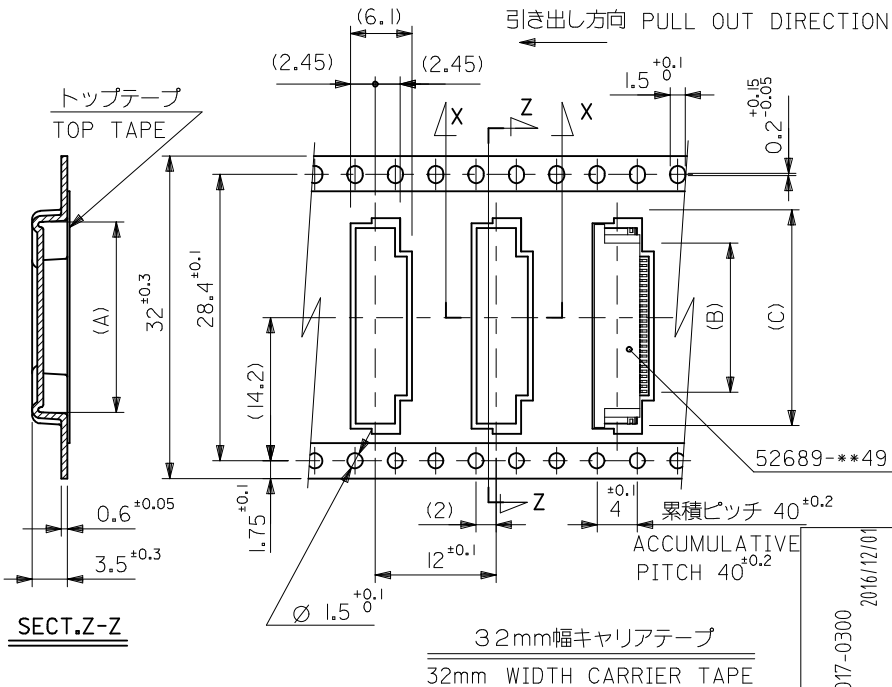
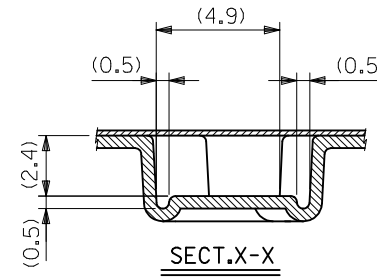
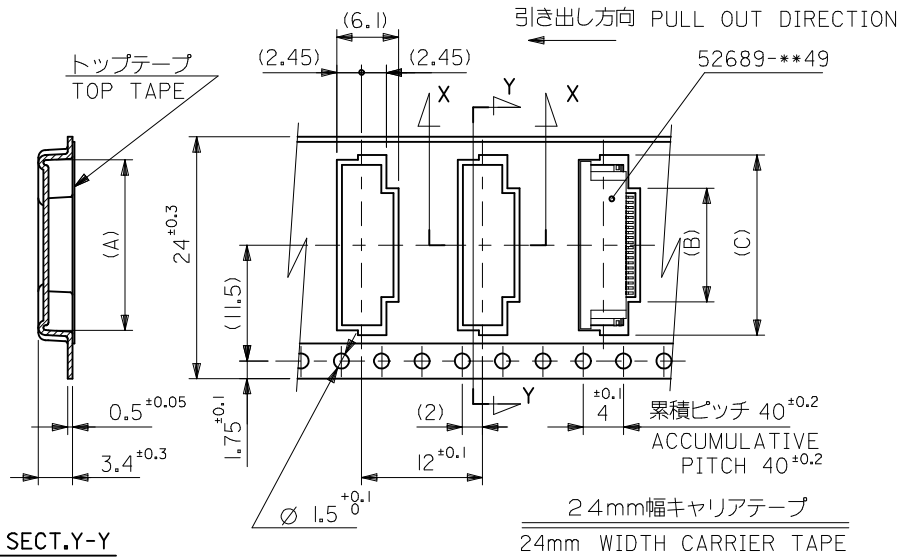
- 本製品は52689-***93の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 52689-***93.

- FPCについて：
打抜き方向は導体側から補強板側を推奨致します。
補強フォルム材質はポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。

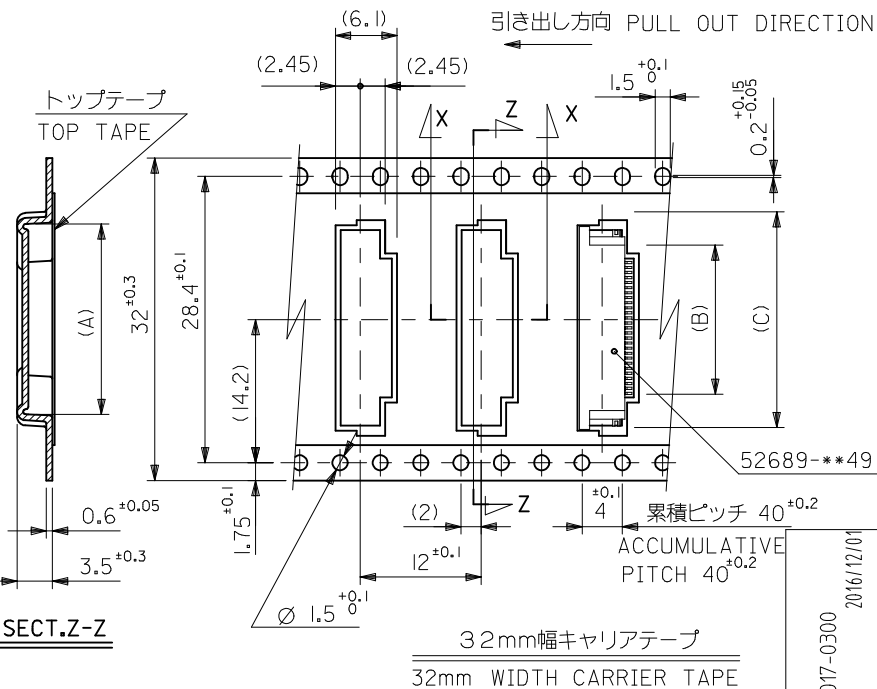
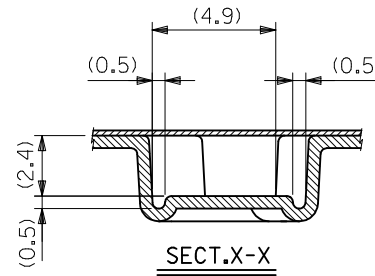
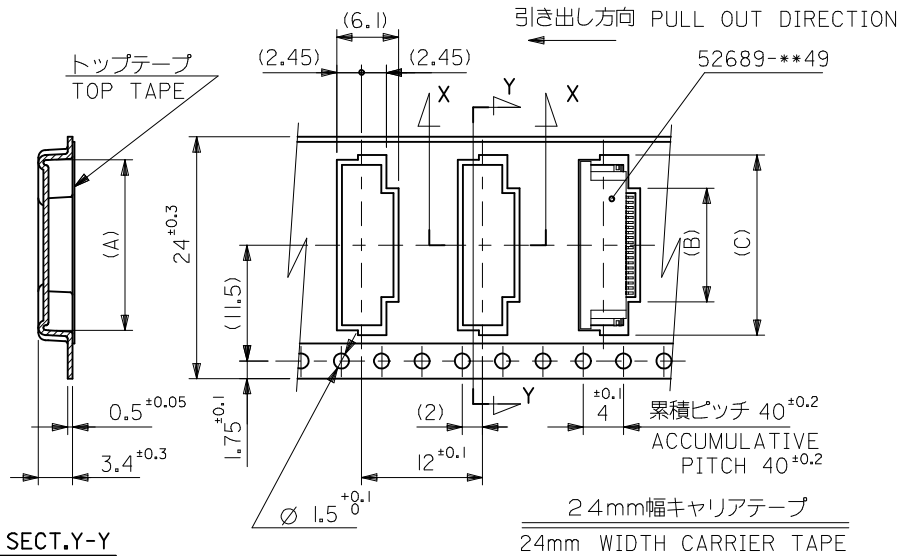
ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION :
FORM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED MATERIAL :
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

- 本製品は乾燥剤入り、ハイバリア梱包仕様である。
THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.

REVISED EC NO: J2017-0300 DRAWINGS CHKD: APPR:MSASAO	DESCRIPTION 2016/12/01 2016/12/20	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		0.25 UNDER UNDER ±0.03	0.25 OVER 0.5 UNDER ±0.05	0.5 OVER 1.0 UNDER ±0.1	1.0 OVER 10 UNDER ±0.2	10 OVER 30 UNDER ±0.25	30 OVER ±0.3	ANGULAR ±3	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE A3
				DRAWN BY H.KAWABATA		DATE 2004/02/03		TITLE 0.5 FPC CONN NON ZIF HSG ASSY SMT RA EMBSTP PKG -LEAD FREE-		
				CHECKED BY K.TOJO		DATE 2004/02/03		molex		
				APPROVED BY M.SASAO		DATE 2004/02/03				
				MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
				SEE SHEET 2,3		SD-52689-035		1 OF 3		

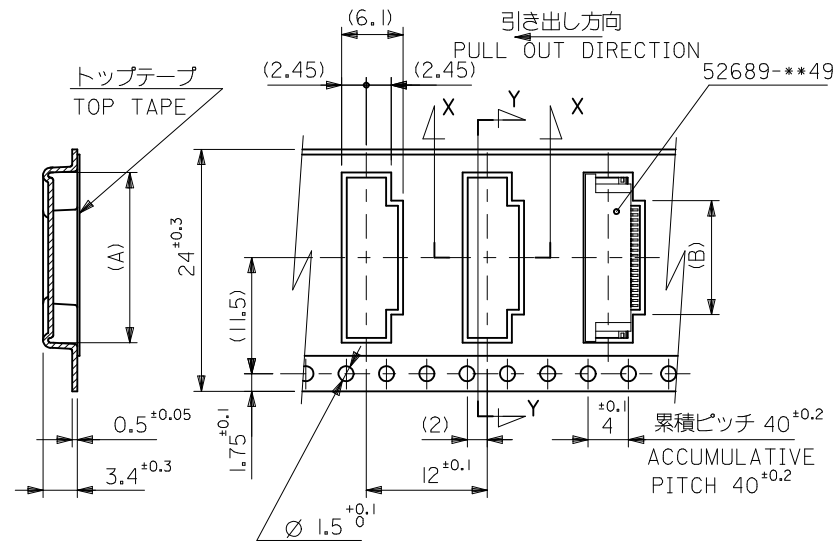


52689-**-87	32	37.4	33.4	22.4	15.8	21.4	52689-3087	30	
MODEL NO.	キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(C)	(B)	(A)	MATERIAL NO.	種数 CIRCUIT	
GENERAL TOLERANCES (UNLESS SPECIFIED)				DIMENSION STYLE		SCALE		DESIGN UNITS	
0.25 UNDER UNDER ±0.03				MM ONLY		---		METRIC	
0.25 OVER 0.5 UNDER ±0.05				DRAWN BY		DATE		TITLE	
0.5 OVER 1.0 UNDER ±0.1				H.KAWABATA		2004/02/03		0.5 FPC CONN NON ZIF HSG ASSY SMT RA EMBSTP PKG -LEAD FREE-	
1.0 OVER 10 UNDER ±0.2				CHECKED BY		DATE			
10 OVER 30 UNDER ±0.25				K.TOJO		2004/02/03			
30 OVER ±0.3				APPROVED BY		DATE		DOCUMENT NO.	
ANGULAR ±				M.SASAO		2004/02/03		SD-52689-035	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				MATERIAL NO.		SEE TABLE		SHEET NO.	
				A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		2 OF 3	



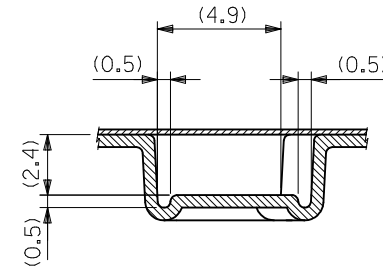
52689-**-87	32	37.4	33.4	22.4	15.8	21.4	52689-3087	30
MODEL NO.	キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(C)	(B)	(A)	MATERIAL NO.	種数 CIRCUIT

REVISED EC NO: J2017-0300 DRAWNGES 2016/12/01 CHKD: APPR:MSASAO 2016/12/20	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
	MM ONLY		---		METRIC		◎ □	
	0.25 UNDER	UNDER	±0.03	DRAWN BY	DATE	TITLE		
	0.25 OVER	0.5 UNDER	±0.05	H.KAWABATA	2004/02/03	0.5 FPC CONN NON ZIF HSG ASSY SMT RA EMBSTP PKG -LEAD FREE-		
0.5 OVER	1.0 UNDER	±0.1	CHECKED BY	DATE	molex DOCUMENT NO. SD-52689-035 SHEET NO. 2 OF 3			
1.0 OVER	10 UNDER	±0.2	K.TOJO	2004/02/03				
10 OVER	30 UNDER	±0.25	APPROVED BY	DATE	SEE TABLE THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
30 OVER		±0.3	M.SASAO	2004/02/03				
ANGULAR	±		MATERIAL NO.					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE					
			A3					



SECT.Y-Y

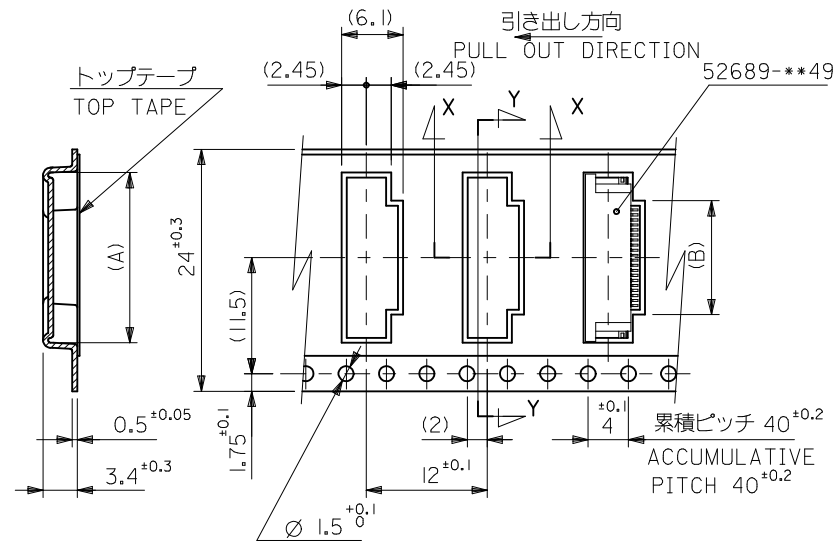
24mm幅キャリアテープ
24mm WIDTH CARRIER TAPE



SECT.X-X

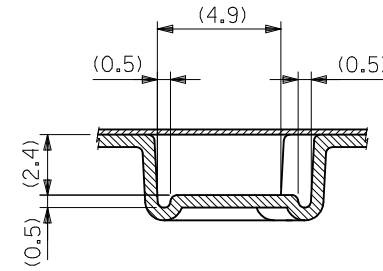
24	29.4	25.4	11.8	17.4	52689-2287	22
52689-***87	キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(B)	(A)	MATERIAL NO. 極数 CIRCUIT

REVISED EC NO: J2017-0300 DRAWN: 2016/12/14 CHKD: APPR: MSASAO 2016/12/20	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±0.03	DRAWN BY	DATE	TITLE		
	0.25 OVER	0.5 UNDER	±0.05	H. KAWABATA	2004/02/03	0.5 FPC CONN NON ZIF HSG ASSY SMT RA EMBSTP PKG -LEAD FREE-		
	0.5 OVER	1.0 UNDER	±0.1	CHECKED BY	DATE	molex		
1.0 OVER	10 UNDER	±0.2	K. TOJO	2004/02/03	DOCUMENT NO.			
10 OVER	30 UNDER	±0.25	APPROVED BY	DATE	SD-52689-035		3 OF 3	
30 OVER		±0.3	M. SASAO	2004/02/03	SEE TABLE			
ANGULAR	±3		MATERIAL NO.		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE A3					



SECT.Y-Y

24mm幅キャリアテープ
24mm WIDTH CARRIER TAPE



SECT.X-X

24	29.4	25.4	11.8	17.4	52689-2287	22
52689-***87	キャリアテープ幅	E	D	(B)	(A)	極数
MODEL NO.	CARRIER TAPE WIDTH					CIRCUIT

REVISED EC NO: J2017-0300 DRAWNGES 2016/12/14 CHKD: APPR:MSASAO 2016/12/20	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±0.03	DRAWN BY	DATE	TITLE		
	0.25 OVER	0.5 UNDER	±0.05	H.KAWABATA	2004/02/03	0.5 FPC CONN NON ZIF HSG ASSY SMT RA EMBSTP PKG		
	0.5 OVER	1.0 UNDER	±0.1	CHECKED BY	DATE	-LEAD FREE-		
	1.0 OVER	10 UNDER	±0.2	K.TOJO	2004/02/03	molex DOCUMENT NO. SD-52689-035 SHEET NO. 3 OF 3		
10 OVER	30 UNDER	±0.25	APPROVED BY	DATE				
30 OVER		±0.3	M.SASAO	2004/02/03				
ANGULAR	±3		MATERIAL NO.		SEE TABLE			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			